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Abstract
The paper gives an analysis on the effect of probing test on solder bump for bare die products. Performance matrices include bump height, probe mark area, contact force, contact probe times, and cleaning pin strategy are discussed. Experimental results show that the coplanarity and structure of bump may be damaged when the contact force and contact probe times are larger than 6mils and 3 times, respectively. This prediction model is proved to be successful on improving the test quality of known good die (KGD) products in the ASE Company.
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